

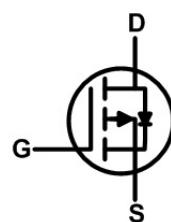
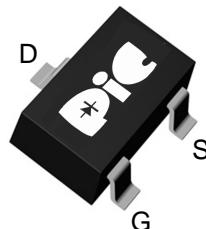
➤ General Description

This PAP0117N P-Channel enhancement mode power field effect transistor is the high density trench technology and this advanced technology can provide excellent Rds(On) performance and efficiency for power switching and load switching application., this device also comply with the RoHS and Green Product requirement with full function reliability approved.

➤ Feature

- Super Low Gate Charge
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology
- SOT-23 Package design

➤ SOT-23



➤ Application

- Load Switch
- Portable instrument
- MB / NB / 3C device

➤ Absolute Maximum Ratings

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	-100	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current, $V_{GS} @ -10V^1$	$I_D @ T_A = 25^\circ C$	-0.9	A
Continuous Drain Current, $V_{GS} @ -10V^1$	$I_D @ T_A = 70^\circ C$	-0.7	A
Pulsed Drain Current ²	I_{DM}	-1.8	A
Total Power Dissipation ³	$P_D @ T_A = 25^\circ C$	1	W
Storage Temperature Range	T_{STG}	-55 to 150	$^\circ C$
Operating Junction Temperature Range	T_J	-55 to 150	$^\circ C$
Thermal Resistance Junction-ambient ¹	$R_{\theta JA}$	125	$^\circ C/W$
Thermal Resistance Junction-Case ¹	$R_{\theta JC}$	80	$^\circ C/W$

➤ **Electrical Characteristics (T_J=25°C Unless otherwise noted)**

Parameter	Symbol	Conditions	Min.	Typ.	Max.		Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V , I _D =-250uA	-100	---	---		V
BVDSS Temperature Coefficient	ΔBV _{DSS} /ΔT _J	Reference to 25°C , I _D =-1mA	---	-0.00624	---		V/°C
Static Drain-Source On-Resistance ²	R _{DS(ON)}	V _{GS} =-10V , I _D =-0.8A	---	0.52	0.65		Ω
		V _{GS} =-4.5V , I _D =-0.4A	---	0.56	0.7		
Gate Threshold Voltage	V _{GS(th)}	V _{GS} =V _{DS} , I _D =-250uA	-1.0	-1.5	-2.5		V
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)}		---	4.5	---		mV/°C
Drain-Source Leakage Current	I _{DSS}	V _{DS} =-80V , V _{GS} =0V , T _J =25	---	---	10		uA
		V _{DS} =-80V , V _{GS} =0V , T _J =55	---	---	100		
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V , V _{DS} =0V	---	---	±100		nA
Forward Transconductance	g _{fs}	V _{DS} =-5V , I _D =-0.8A	---	3	---		S
Gate Resistance	R _g	V _{DS} =0V , V _{GS} =0V , f=1MHz	---	16	32		Ω
Total Gate Charge (-4.5V)	Q _g	V _{DS} =-15V , V _{GS} =-4.5V , I _D =-0.5A	---	4.5	---		nC
Gate-Source Charge	Q _{gs}		---	1.14	---		
Gate-Drain Charge	Q _{gd}		---	1.5	---		
Turn-On Delay Time	T _{d(on)}	V _{DD} =-50V , V _{GS} =-10V , R _G =3.3Ω I _D =-0.5A	---	13.6	---		ns
Rise Time	T _r		---	6.8	---		
Turn-Off Delay Time	T _{d(off)}		---	34	---		
Fall Time	T _f		---	3	---		
Input Capacitance	C _{iss}	V _{DS} =-15V , V _{GS} =0V , f=1MHz	---	553	---		pF
Output Capacitance	C _{oss}		---	29	---		
Reverse Transfer Capacitance	C _{rss}		---	20	---		

➤ **Diode Characteristics**

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Continuous Source Current ^{1,4}	I _s	V _G =V _D =0V , Force Current	---	---	-0.9	A
Pulsed Source Current ^{2,4}	I _{SM}		---	---	-1.8	A
Diode Forward Voltage ²	V _{SD}	V _{GS} =0V , I _s =-1A , T _J =25°C	---	---	-1.2	V

Note :

1.Pulse width limited by maximum junction temperature.

2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%

3.Ensure that the channel temperature does not exceed 150°C.

4.The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

➤ **Typical Characteristics**

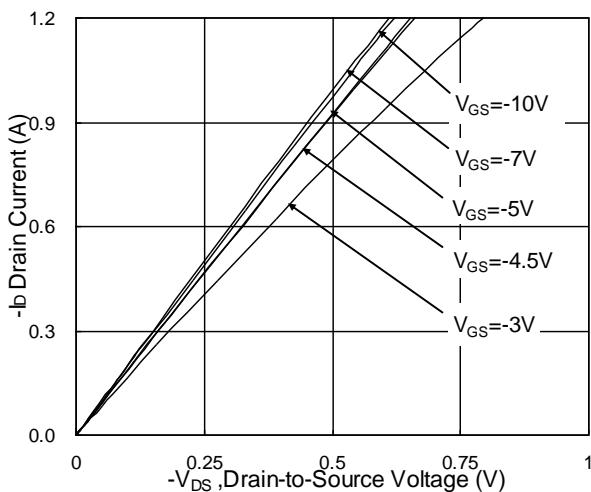


Fig.1 Typical Output Characteristics

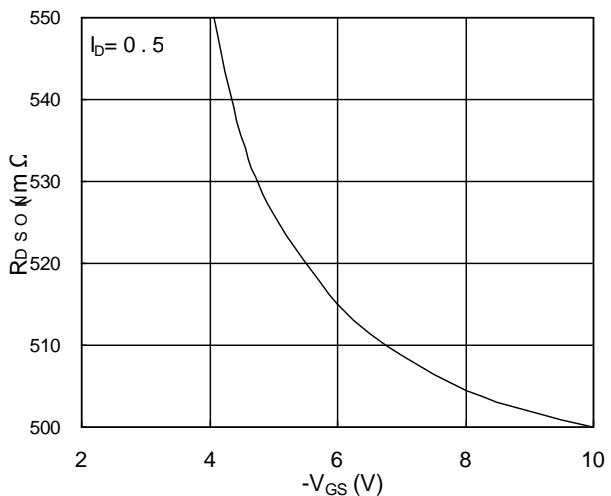


Fig.2 On-Resistance vs. Gate-Source

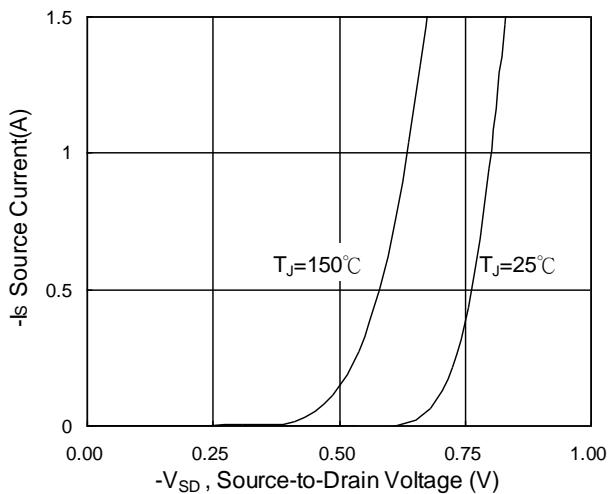


Fig.3 Forward Characteristics Of Reverse

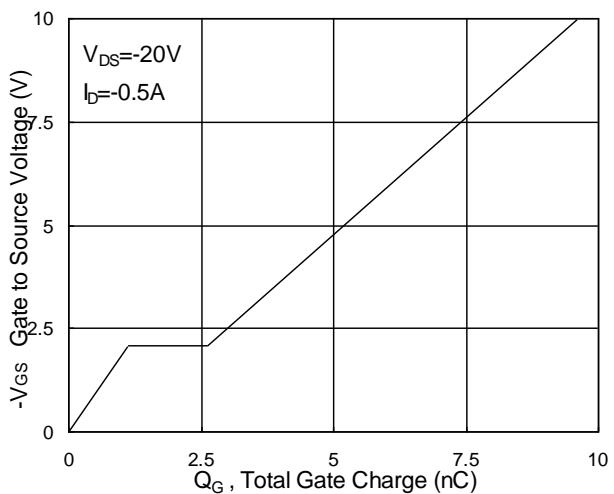


Fig.4 Gate-Charge Characteristics

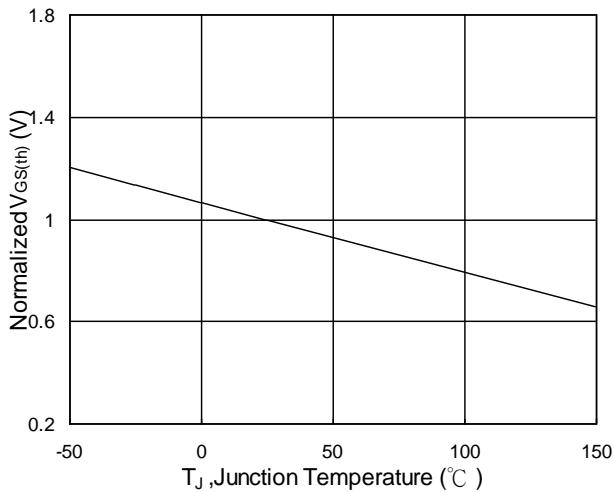


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

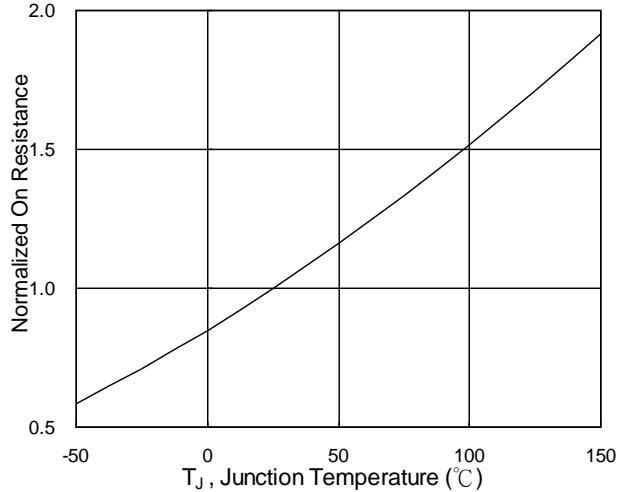
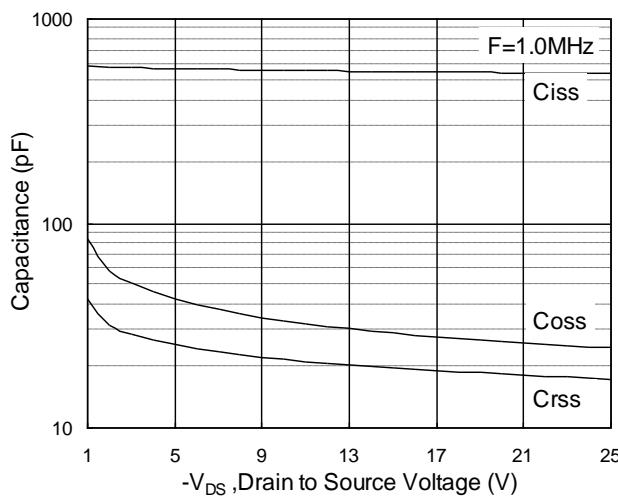
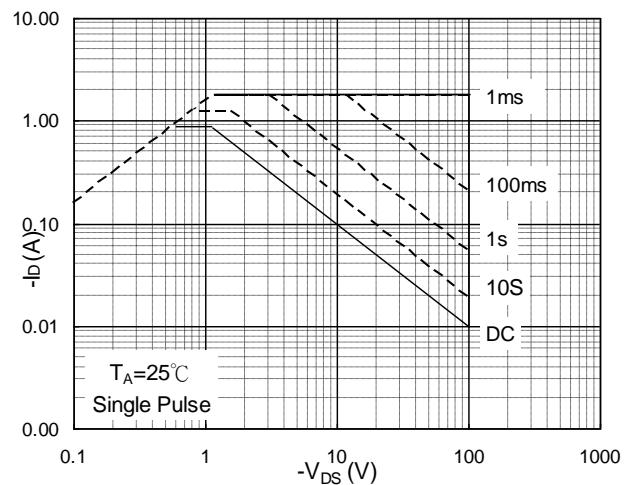
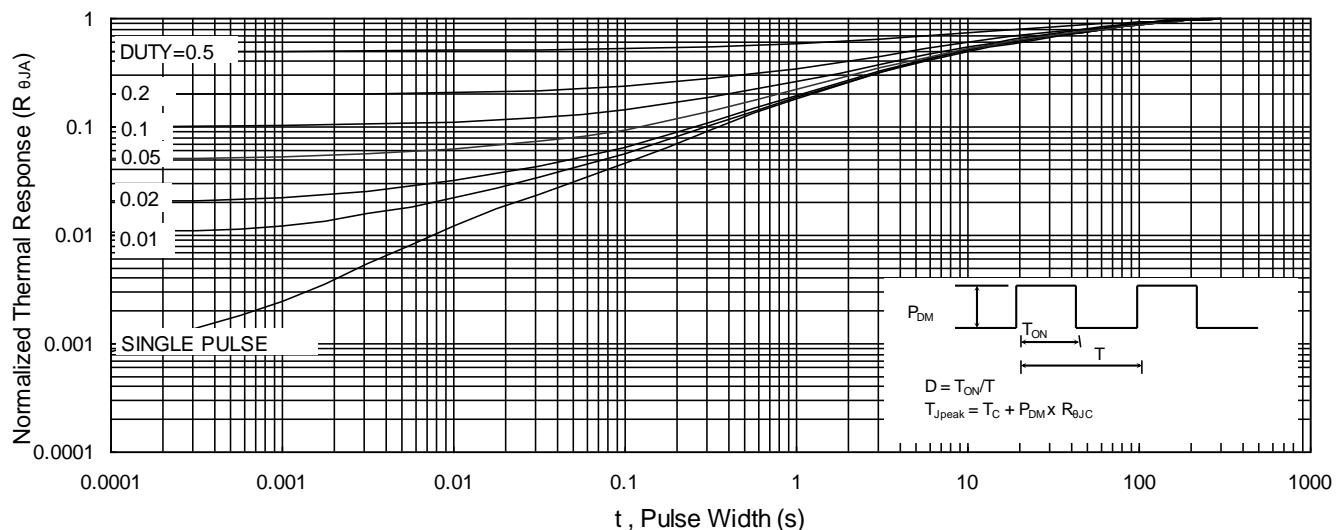
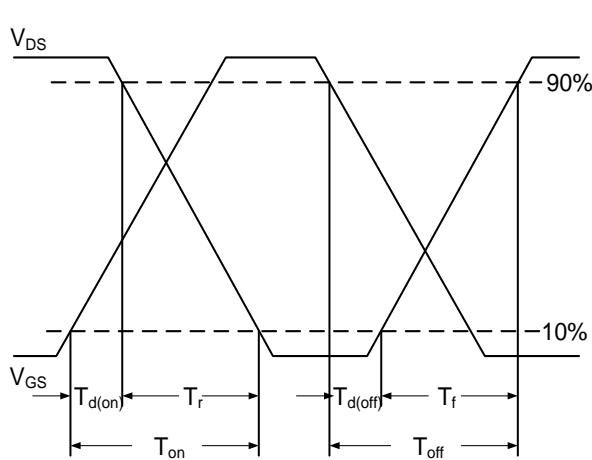
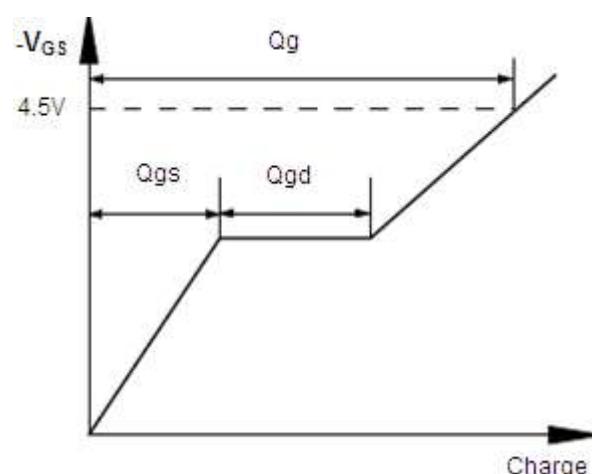
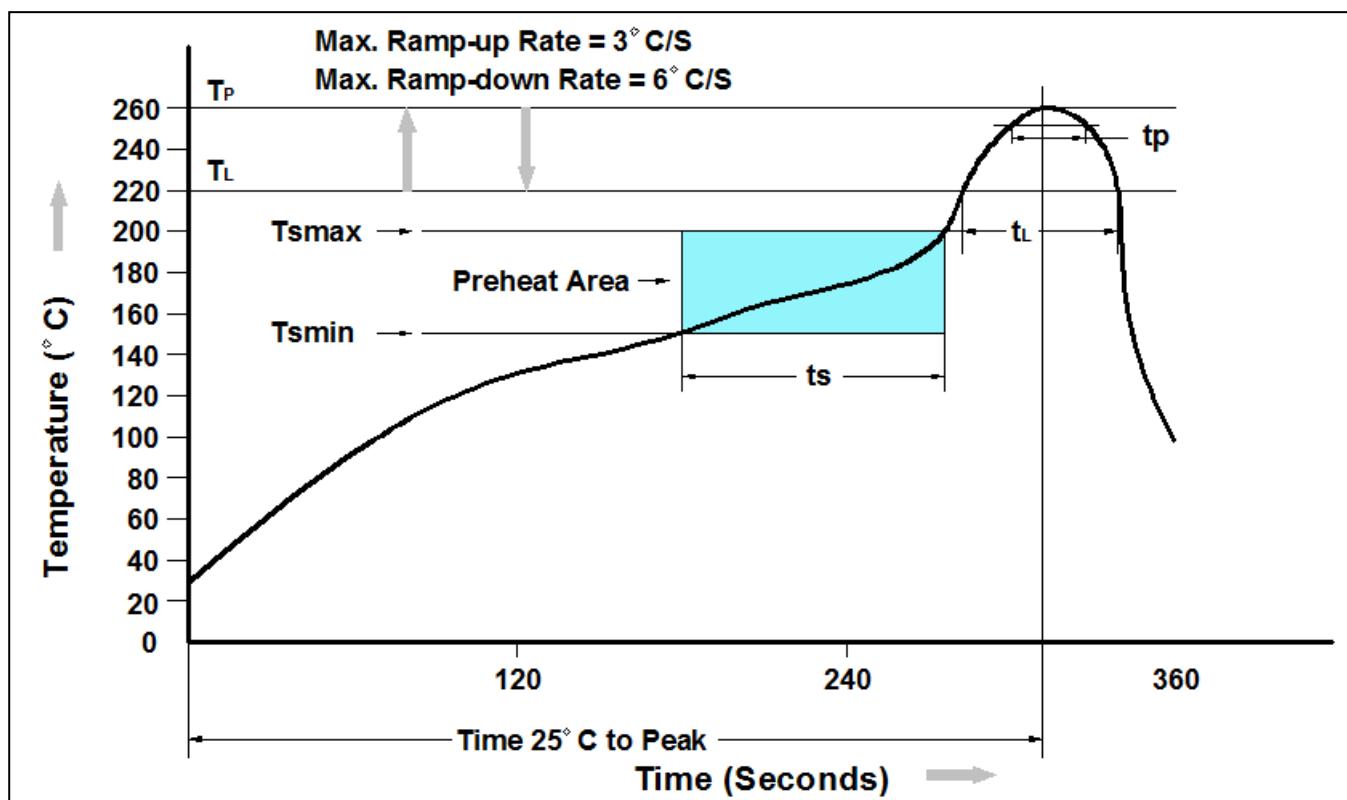


Fig.6 Normalized $R_{DS(on)}$ vs. T_J


Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Gate Charge Waveform

➤ Recommand IR Reflow Soldering Thermal Profile

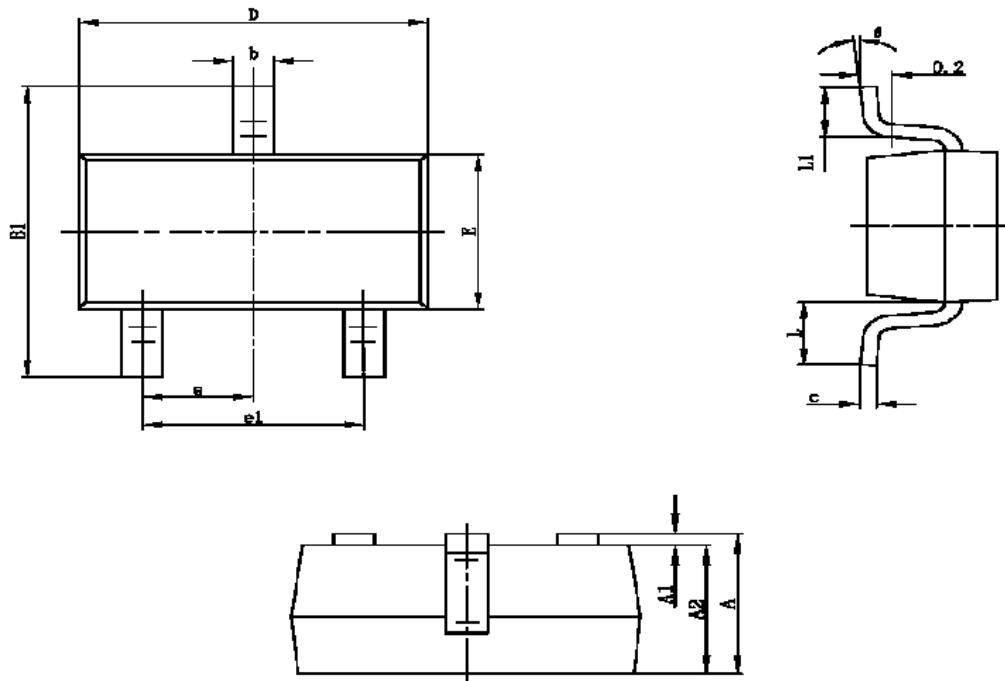


Profile Feature	Pb-Free Assembly Profile
Temperature Min. (T _{smin})	150°C
Temperature Max. (T _{smax})	200°C
Time (t _s) from (T _{smin} to T _{smax})	60-120 seconds
Average Ramp-up Rate (t _L to t _P)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of actual Peak Temperature	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.

➤ Ordering Information

Part Number	Description	Quantity
PAP0117N	SOT-23 Reel	3000 pcs

➤ **Package Information (SOT- 23)**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.400	0.012	0.016
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.700REF		0.028REF	
L1	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

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